



Material Content Data Sheet



Sales Product Name				IPD70N04S3-07		Issued		20. July 2018	
MA#				MA000370563					
Package				PG-TO252-3-11		Weight*		370.99 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.588	0.70	0.70	6976	6976	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174		
	non noble metal	iron	7439-89-6	0.215	0.06		580		
	non noble metal	copper	7440-50-8	215.017	57.94	58.02	579568	580322	
	non noble metal	aluminium	7429-90-5	4.733	1.28	1.28	12757	12757	
wire	non noble metal	aluminium	7429-90-5	4.733	1.28	1.28	12757	12757	
encapsulation	organic material	carbon black	1333-86-4	1.229	0.33		3313		
	plastics	epoxy resin	-	21.508	5.80		57972		
	inorganic material	silicondioxide	60676-86-0	100.164	27.00	33.13	269986	331271	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10081	10081	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246	
solder	non noble metal	tin	7440-31-5	0.049	0.01		132		
	noble metal	silver	7440-22-4	0.061	0.02		165		
	non noble metal	lead	7439-92-1	2.333	0.63	0.66	6290	6587	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	iron	7439-89-6	0.019	0.01		52		
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51692	51760	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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